

TOPCon正面细栅浆料
TOPCon Front-Side Finger Paste

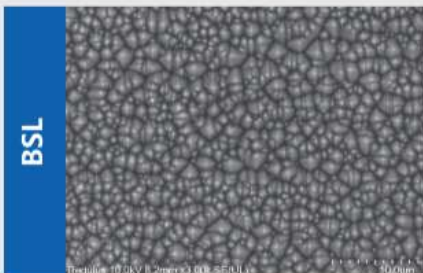
GN33L系列
GN33L Series

适用范围
Application

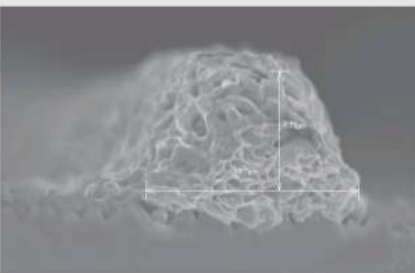
- 适用于TOPCon电池技术路线的正面激光辅助烧结浆料，适配超细线钢版/PI网版，适配各种烧结炉/光注入炉/激光等设备
Laser-assisted firing paste designed for the front-side metallization of TOPCon cell technology. Compatible with ultra-fine line stainless steel stencils / PI (polyimide) screens, and compatible with various sintering furnaces, light-injection (photonic curing) furnaces, and laser equipment.

亮点
Highlights

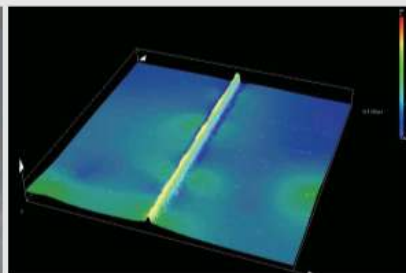
- 极佳的过墨能力，适配超细开口（3-8 μ m线宽）实现高速印刷量产
Excellent paste transfer capability, compatible with ultra-fine screen openings (3-8 μ m finger width), enabling high-speed mass production printing.
- 较宽的工艺窗口，在超低单耗情况下仍具有优异的电性能及可靠性表现
Wide process window, delivering excellent electrical performance and reliability even under ultra-low specific consumption (paste usage).
- 精准把控腐蚀能力，控制好Uoc与FF平衡，确保极高EL良率
Precise control of etching/contact capability, maintaining an optimized balance between Uoc (Open-circuit voltage) and FF (Fill Factor), ensuring extremely high EL (Electroluminescence) yield.
- 优异的印刷性能同时可以保证极佳的高宽比且边缘干净无毛刺
Superior printing performance that simultaneously ensures an excellent aspect ratio with clean, burr-free edge profiles.



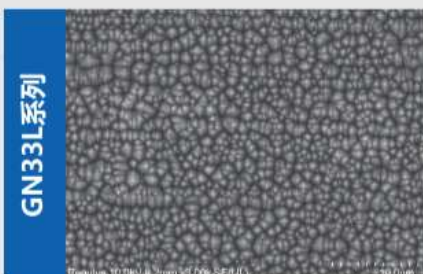
接触点
Contact points



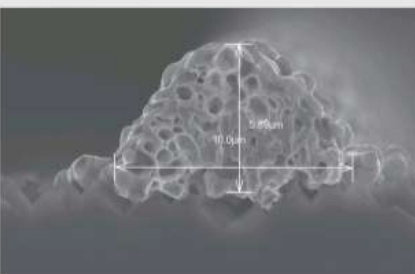
高宽比53.1%
Aspect ratio 53.1%



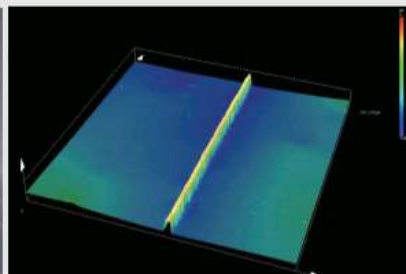
线型起伏且毛刺较多
Non-uniform line profiles with significant burrs



良好接触点
Well-formed contact points



高宽比58.9%
Aspect ratio 58.9%



规整顺滑无毛刺
Uniform, smooth, and burr-free profiles